AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A method~~,~~ comprising:

applying a thermoplastic bonder to the perimeter of a ball grid array (BGA) package, wherein the thermoplastic bonder is applied to the BGA package directly between a first surface and a second surface of the BGA package;

applying the thermoplastic bonder to ~~an array of~~ solder balls of the BGA package, ~~included in the BGA package~~wherein the thermoplastic bonder is applied to the solder balls between the first surface of the BGA package and the solder balls, and between the second surface of the BGA package and the solder balls~~, independent of the applying of the thermoplastic bonder to the perimeter of the BGA package~~; and

attaching a printable circuit board (PCB) to the BGA package ~~via the thermoplastic bonder on the perimeter of the BGA package and the array of solder balls with the thermoplastic bonder~~.

2. (Previously Presented) The method of claim 1, wherein the BGA package comprises~~:~~ an integrated circuit (IC) device~~;~~

~~a first surface coupled with the IC device; and~~

~~solder joints to attach the array of solder balls with the first surface and a second surface~~.

3. (Previously Presented) The method of claim 1, wherein the ~~applying of the thermoplastic bonder comprises applying the bonder between the~~ first surface comprise a top surface, and the second surface comprises a bottom surface~~to provide resistance to the BGA package against warpage~~.

4. (Previously Presented) The method of claim ~~3~~ 1, ~~wherein the~~ further comprising preventing warpage of the BGA package by applying the thermoplastic bonder in a weak area of the BGA package, the weak area including the perimeter of the BGA package~~comprises at least one~~ ; wherein the BGA package includes one or more of an opening of the BGA pacakge, a cracking of the BGA pacakge, a curving of the BGA package, bending, and a breaking of the ~~second surface~~ BGA package.

5. (Previously Presented) The method of claim 1, wherein the applying of the thermoplastic bonder to the perimeter of the BGA package further comprises applying the thermoplastic bonder exclusively to the perimeter of the BGA package, wherein the perimeter includes ~~is further applied to~~ one or more of edges and corners of the BGA package.

6. (Previously Presented) The method of claim ~~1~~ 4, further comprising determining the weak area of the BGA package to prevent the warpage~~wherein the applying of the thermoplastic bonder comprises applying the thermoplastic bonder using a bonder dispenser~~.

7. (Cancelled)

8. (Previously Presented) The method of claim 1, wherein the ~~applying of the~~ thermoplastic bonder ~~comprises using~~ is applied via one or more of a hot melting jig ~~or~~ and a dispenser~~, the hot melting jig and the dispenser comprise at least one of a hot melt hand applicator and an adhesive unit~~.

9. (Cancelled)

10. (Previously Presented) The method of claim ~~1~~ 8, wherein the ~~independent application of the~~ thermoplastic bonder is further applied via ~~performed using~~

software to control placement distance of the thermoplastic bonder ~~with respect~~ to the ~~array of~~ perimeter of the BGA package with respect to the solder balls of the BGA package.

11-31 (Cancelled)